

In the production of a high frequency circuit chip in which a wiring pattern is disposed on a substrate having a through-hole, a connecting electrode of the through-hole is formed by filling electrically conductive paste into a perforation and firing it, and the wiring pattern is formed by a lift-off method. Moreover, at least the surface of the substrate for the wiring pattern to be formed thereon is mirror-polished, and thereafter, the wiring pattern is formed on the mirror-polished surface by the lift-off method.